# High-Speed USB 2.0 (480 Mbps) DPDT Switches

The NL3S2223 is a DPDT switch optimized for high–speed USB 2.0 applications within portable systems. It features ultra–low on capacitance,  $C_{\rm ON}=5.5$  pF (typ), and a bandwidth above 950 MHz. It is optimized for applications that use a single USB interface connector to route multiple signal types. The  $C_{\rm ON}$  and  $R_{\rm ON}$  of both channels are suitably low to allow the NL3S2223 to pass any speed USB data or audio signals going to a moderately resistive terminal such as an external headset. The device is offered in a UQFN10 1.4 mm x 1.8 mm package.



• Optimized Flow-Through Pinout

•  $R_{ON}$ : 5.0  $\Omega$  Typ @  $V_{CC} = 4.2 \text{ V}$ 

•  $C_{ON}$ : 5.5 pF Typ @  $V_{CC}$  = 3.3 V

• V<sub>CC</sub> Range: 1.65 V to 4.5 V

• Typical Bandwidth: 950 MHz

• 1.4 mm x 1.8 mm x 0.50 mm UQFN10

• OVT on Common Signal Pins D+/D- up to 5.25 V

• 8 kV HBM ESD Protection on All Pins

 These Devices are Pb–Free, Halogen Free/BFR Free and are RoHS Compliant

## **Typical Applications**

• High Speed USB 2.0 Data

• Mobile Phones

• Portable Devices

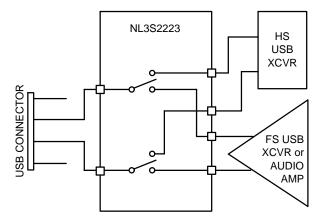


Figure 1. Application Diagram



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## MARKING DIAGRAM



UQFN10 CASE 488AT



U3 = Device Code

M = Date Code

Pb-Free Device

(Note: Microdot may be in either location)

#### ORDERING INFORMATION

Device	Package	Shipping <sup>†</sup>		
NL3S2223MUTBG	UQFN10 (Pb-Free)	3000 / Tape & Reel		

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

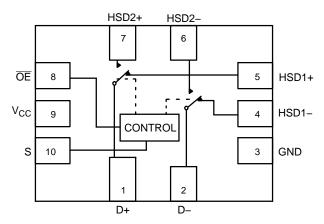


Figure 2. Pin Connections and Logic Diagram (Top View)

### **Table 1. PIN DESCRIPTION**

Pin	Function
S	Control Input
ŌĒ	Output Enable
HSD1+, HSD1-, HSD2+, HSD2-, D+, D-	Data Ports

#### **Table 2. TRUTH TABLE**

ŌĒ	S	HSD1+, HSD1-	HSD2+, HSD2-
1	X	OFF	OFF
0	0	ON	OFF
0	1	OFF	ON

### **MAXIMUM RATINGS**

Symbol	Pins	Parameter	Value	Unit
V <sub>CC</sub>	V <sub>CC</sub>	Positive DC Supply Voltage	-0.5 to +5.5	V
V <sub>IS</sub>	HSDn+, HSDn-	Analog Signal Voltage	-0.5 to V <sub>CC</sub> + 0.3	V
	D+, D-	1 Γ	-0.5 to +5.25	
V <sub>IN</sub>	S, <del>OE</del>	Control Input Voltage, Output Enable Voltage	-0.5 to +5.5	V
Icc	V <sub>CC</sub>	V <sub>CC</sub> Positive DC Supply Current		mA
T <sub>S</sub>		Storage Temperature	-65 to +150	°C
I <sub>IS_CON</sub>	HSDn+, HSDn–, D+, D–	Analog Signal Continuous Current–Closed Switch	±300	mA
I <sub>IS_PK</sub>	HSDn+, HSDn-, D+, D-	Analog Signal Continuous Current 10% Duty Cycle	±500	mA
I <sub>IN</sub>	S, <del>OE</del>	Control Input Current, Output Enable Current	±20	mA
V <sub>ESD</sub>	HBM MM	Human Body Model Machine Model	8 400	kV V
I <sub>Latchup</sub>		Latchup Performance	±100	mA

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

## **RECOMMENDED OPERATING CONDITIONS**

Symbol	Pins	Parameter	Min	Max	Unit
$V_{CC}$		Positive DC Supply Voltage	1.65	4.5	V
$V_{IS}$	HSDn+, HSDn-	Analog Signal Voltage	GND	V <sub>CC</sub>	V
	D+, D-		GND	4.5	
V <sub>IN</sub>	S, <del>OE</del>	Control Input Voltage, Output Enable Voltage	GND	V <sub>CC</sub>	V
T <sub>A</sub>		Operating Temperature	-40	+85	°C

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

## DC ELECTRICAL CHARACTERISTICS

## **CONTROL INPUT, OUTPUT ENABLE VOLTAGE** (Typical: T = 25°C)

					-40°C to +85°C			
Symbol	Pins	Parameter	Test Conditions	V <sub>CC</sub> (V)	Min	Тур	Max	Unit
V <sub>IH</sub>	S, ŌE	Control Input, Output Enable HIGH Voltage (See Figure 11)		2.7 3.3 4.2	1.25 1.3 1.4	-	-	٧
V <sub>IL</sub>	S, <del>OE</del>	Control Input, Output Enable LOW Voltage (See Figure 11)		2.7 3.3 4.2	-	-	0.35 0.4 0.5	V
I <sub>IN</sub>	S, <del>OE</del>	Current Input, Output Enable Leakage Current	$0 \le V_{IS} \le V_{CC}$	1.65 – 4.5	-	-	±0.1	μΑ

## **SUPPLY CURRENT AND LEAKAGE** (Typical: T = $25^{\circ}$ C, $V_{CC} = 3.3 \text{ V}$ )

					-4	–40°C to +85°C		
Symbol	Pins	Parameter	Test Conditions	V <sub>CC</sub> (V)	Min	Тур	Max	Unit
I <sub>CC</sub>	V <sub>CC</sub>	Quiescent Supply Current	$0 \le V_{IS} \le V_{CC}$ ; $I_D = 0 \text{ A}$ $0 \le V_{IS} \le V_{CC} - 0.5 \text{ V}$	1.65 – 3.6 3.6 – 4.5	- -	- -	0.1 0.1	μΑ
I <sub>OZ</sub>		OFF State Leakage	$0 \le V_{IS} \le V_{CC}$	1.65 – 4.5	-	±0.1	±0.5	μΑ
l <sub>OFF</sub>	D+, D-	Power OFF Leakage Current	$0 \le V_{IS} \le V_{CC}$	0	_	-	±0.5	μΑ

## **LIMITED V<sub>IS</sub> SWING ON RESISTANCE** (Typical: T = 25°C)

					–40°C to +85°C			
Symbol	Pins	Parameter	Test Conditions	V <sub>CC</sub> (V)	Min	Тур	Max	Unit
R <sub>ON</sub>		On–Resistance (Note 1)	I <sub>ON</sub> = 8 mA V <sub>IS</sub> = 0 V to 0.4 V	2.7 3.3 4.2	-	6.0 5.5 5.0	8.6 7.6 7.0	Ω
R <sub>FLAT</sub>		On–Resistance Flatness (Notes 1 and 2)	I <sub>ON</sub> = 8 mA V <sub>IS</sub> = 0 V to 0.4 V	2.7 3.3 4.2	-	0.55 0.30 0.20	-	Ω
ΔR <sub>ON</sub>		On–Resistance Matching (Notes 1 and 3)	I <sub>ON</sub> = 8 mA V <sub>IS</sub> = 0 V to 0.4 V	2.7 3.3 4.2	-	0.60 0.60 0.60	-	Ω

<sup>1.</sup> Guaranteed by design.

## FULL $V_{IS}$ SWING ON RESISTANCE (Typical: T = 25°C)

					–40°C to +85°C			
Symbol	Pins	Parameter	Test Conditions	V <sub>CC</sub> (V)	Min	Тур	Max	Unit
R <sub>ON</sub>		On-Resistance	I <sub>ON</sub> = 8 mA V <sub>IS</sub> = 0 V to V <sub>CC</sub>	2.7 3.3 4.2	-	10 8.0 7.0	13.5 9.75 8.50	Ω
R <sub>FLAT</sub>		On–Resistance Flatness (Notes 4 and 5)	I <sub>ON</sub> = 8 mA V <sub>IS</sub> = 0 V to V <sub>CC</sub>	2.7 3.3 4.2	-	4.5 3.0 2.5	-	Ω
ΔR <sub>ON</sub>		On–Resistance (Note 4 and 6)	$I_{ON} = 8 \text{ mA}$ $V_{IS} = 0 \text{ V to } V_{CC}$	2.7 3.3 4.2	-	0.60 0.60 0.60	-	Ω

<sup>4.</sup> Guaranteed by design.

Flatness is defined as the difference between the maximum and minimum value of On–Resistance as measured over the specified analog signal ranges.

<sup>3.</sup>  $\Delta \ddot{R}_{ON} = \ddot{R}_{ON(max)} - R_{ON(min)}$  between HSD1<sup>+</sup> and HSD1<sup>-</sup> or HSD2<sup>+</sup> and HSD2<sup>-</sup>.

Flatness is defined as the difference between the maximum and minimum value of On–Resistance as measured over the specified analog signal ranges.

<sup>6.</sup>  $\Delta R_{ON} = R_{ON(max)} - R_{ON(min)}$  between HSD1+ and HSD1- or HSD2+ and HSD2-.

## **AC ELECTRICAL CHARACTERISTICS**

**TIMING/FREQUENCY** (Typical: T = 25°C,  $V_{CC}$  = 3.3 V,  $R_L$  = 50  $\Omega$ ,  $C_L$  = 35 pF, f = 1 MHz)

					-40°C to +85°C			
Symbol	Pins	Parameter	Test Conditions	V <sub>CC</sub> (V)	Min	Тур	Max	Unit
t <sub>ON</sub>	Closed to Open	Turn-ON Time (See Figures 4 and 5)		1.65 – 4.5	-	13.0	30.0	ns
t <sub>OFF</sub>	Open to Closed	Turn-OFF Time (See Figures 4 and 5)		1.65 – 4.5	-	12.0	25.0	ns
T <sub>BBM</sub>		Break-Before-Make Time (See Figure 3)		1.65 – 4.5	2.0	-	-	ns
BW		−3 dB Bandwidth (See Figure 10)	C <sub>L</sub> = 5 pF	1.65 – 4.5	_	950	-	MHz

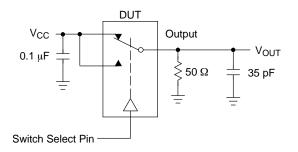
**ISOLATION** (Typical: T = 25°C,  $V_{CC}$  = 3.3 V,  $R_L$  = 50  $\Omega$ ,  $C_L$  = 5 pF)

					-40°C to +85°C			
Symbol	Pins	Parameter	Test Conditions	V <sub>CC</sub> (V)	Min	Тур	Max	Unit
O <sub>IRR</sub>	Open	OFF-Isolation (See Figure 6)	f = 240 MHz	1.65 – 4.5	-	-22	-	dB
X <sub>TALK</sub>	HSDn+ to HSDn-	Non-Adjacent Channel Crosstalk	f = 240 MHz	1.65 – 4.5	-	-24	-	dB

**CAPACITANCE** (Typical: T = 25°C,  $V_{CC}$  = 3.3 V,  $R_L$  = 50  $\Omega$ ,  $C_L$  = 5 pF)

				-4	0°C to +85	s°C	
Symbol	Pins	Parameter	Test Conditions	Min	Тур	Max	Unit
C <sub>IN</sub>	S, OE	Control Pin, Output Enable	V <sub>CC</sub> = 0 V, f = 1 MHz	_	1.5	-	pF
			V <sub>CC</sub> = 0 V, f = 10 MHz	_	1.0	-	
C <sub>ON</sub>	D+ to HSD1+ or		V <sub>CC</sub> = 3.3 V; <del>OE</del> = 0 V, f = 1 MHz S = 0 V or 3.3 V	-	5.5	-	
	HSD2+		V <sub>CC</sub> = 3.3 V; <del>OE</del> = 0 V, f = 10 MHz S = 0 V or 3.3 V	_	5.5	_	
			V <sub>CC</sub> = 3.3 V; <del>OE</del> = 0 V, f = 240 MHz S = 0 V or 3.3 V	_	5	_	
C <sub>OFF</sub>	HSD1n or HSD2n	OFF Capacitance	$V_{CC} = V_{ S} = 3.3 \text{ V};$ $\overline{OE} = 3.3 \text{ V or } (\overline{OE} = 0 \text{ V}, \text{ S} = 3.3 \text{ V or } 0 \text{ V}),$ f = 1  MHz	-	3.8	-	pF
			$V_{CC} = V_{IS} = 3.3 \text{ V};$ $\overline{OE} = 3.3 \text{ V or } (\overline{OE} = 0 \text{ V}, \text{ S} = 3.3 \text{ V or } 0 \text{ V}),$ f = 10  MHz	-	2.0	-	

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.



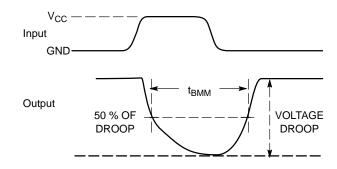
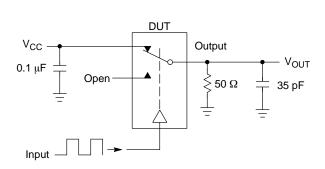


Figure 3. t<sub>BBM</sub> (Time Break-Before-Make)



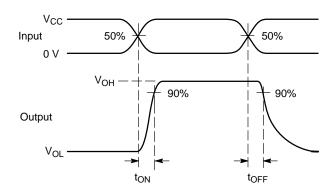
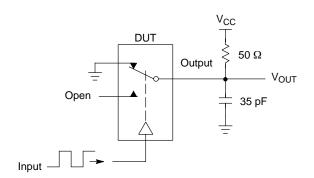


Figure 4. t<sub>ON</sub>/t<sub>OFF</sub>



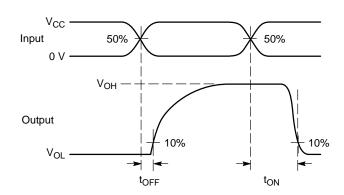
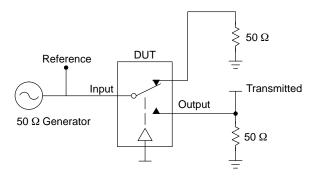


Figure 5. t<sub>ON</sub>/t<sub>OFF</sub>



Channel switch control/s test socket is normalized. Off isolation is measured across an off channel. On loss is the bandwidth of an On switch.  $V_{ISO}$ , Bandwidth and  $V_{ONL}$  are independent of the input signal direction.

$$\begin{split} &V_{ISO} = \text{Off Channel Isolation} = 20 \text{ Log} \left( \frac{V_{OUT}}{V_{IN}} \right) \text{for } V_{IN} \text{ at } 100 \text{ kHz} \\ &V_{ONL} = \text{On Channel Loss} = 20 \text{ Log} \left( \frac{V_{OUT}}{V_{IN}} \right) \text{ for } V_{IN} \text{ at } 100 \text{ kHz to } 50 \text{ MHz} \end{split}$$

Bandwidth (BW) = the frequency 3 dB below  $V_{ONL}$ 

 $\mbox{V}_{\mbox{CT}} = \mbox{Use V}_{\mbox{ISO}}$  setup and test to all other switch analog input/outputs terminated with 50  $\Omega$ 

Figure 6. Off Channel Isolation/On Channel Loss (BW)/Crosstalk (On Channel to Off Channel)/V<sub>ONL</sub>

### **DETAILED DESCRIPTION**

### High Speed (480Mbps) USB 2.0 Optimized

The NL3S2223 is a DPDT switch designed for USB applications within portable systems. The  $R_{\rm ON}$  and  $C_{\rm ON}$  of both switches are maintained at industry–leading low levels in order to ensure maximum signal integrity for USB 2.0 high speed data communication. The NL3S2223 switch can be used to switch between high speed (480Mbps) USB signals and a variety of audio or data signals such as full speed USB, UART or even a moderately resistive audio terminal.

## **Over Voltage Tolerant**

The NL3S2223 features over voltage tolerant I/O protection on the common signal pins D+/D-. This allows the switch to interface directly with a USB connector. The D+/D- pins can withstand a short to  $V_{BUS}$ , up to 5.25 V, continuous DC current for up to 24 hours as specified in the USB 2.0 specification. This protection is achieved without the need for any external resistors or protection devices.

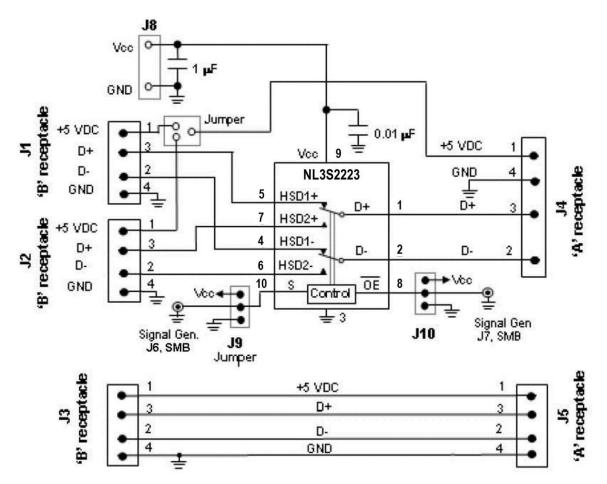


Figure 7. Board Schematic

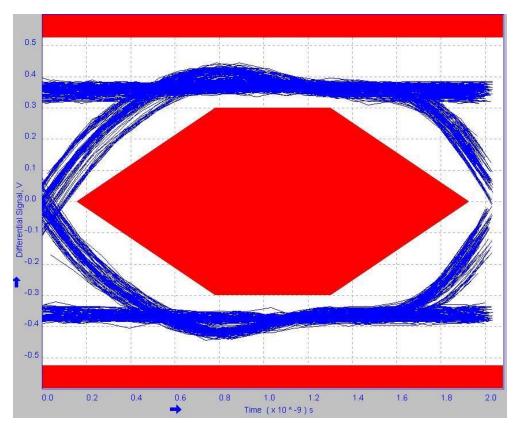


Figure 8. Signal Quality

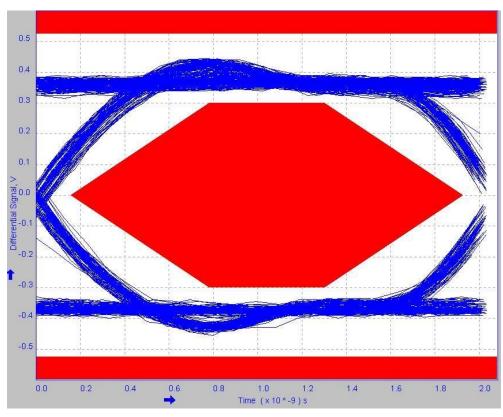


Figure 9. Near End Eye Diagram

Near End Test Data:					Min	Max
Std.	Consecutive jitter range	-54.37	73.21	ps	–200 ps	+200 ps
	Paired JK jitter range	-59.14	59.56	ps		
	Paired KJ jitter range	-50.79	34.57	ps		
	Consecutive jitter range	-74.43	81.65	ps	–200 ps	+200 ps
N.C.	Paired JK jitter range	-61.60	58.55	ps		
	Paired KJ jitter range	-55.31	48.43	ps		
	Consecutive jitter range	-82.55	80.33	ps	–200 ps	+200 ps
N.O.	Paired JK jitter range	-53.50	71.65	ps		
	Paired KJ jitter range	-62.60	47.30	ps		

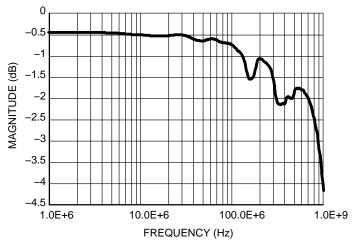


Figure 10. Magnitude vs. Frequency @ V<sub>CC</sub> = 3.3 V, All Temperatures

## I<sub>CC</sub> Leakage Current as a Function of V<sub>IN</sub> Voltage (25°C)

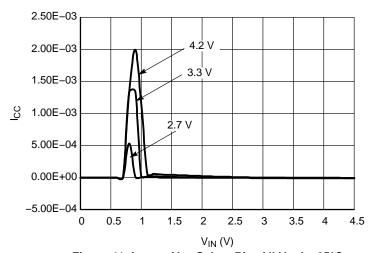


Figure 11.  $I_{CC}$  vs.  $V_{IN}$ , Select Pin, All  $V_{CC}$ 's, 25°C

#### PACKAGE DIMENSIONS

#### UQFN10 1.4x1.8, 0.4P CASE 488AT **ISSUE A EDGE OF PACKAGE** NOTES DIMENSIONING AND TOLERANCING PER ASME Α D Y14.5M, 1994. CONTROLLING DIMENSION: MILLIMETERS DIMENSION 6 APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.25 AND 0.30 MM FROM TERMINAL. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS. E PIN 1 REFERENCE **DETAIL A MILLIMETERS** 2X | | 0.10 | C **Bottom View** MIN MAX 0.45 0.60 (Optional) 0.00 0.05 0.127 REF 0.10 C A3 MOLD CMPD 0.15 0.25 EXPOSED Cu В 1.40 BSC **TOP VIEW** Е 1.80 BSC 0.40 BSC е 0.05 C **A3** 0.30 0.50 0.00 0.15 0.40 0.60 Α1 0.05 C **DETAIL B** Α1 SEATING PLANE Side View **MOUNTING FOOTPRINT\*** SIDE VIEW (Optional) 1.700 0.563 0.0669 0.0221 0.663 0.0261 0.200 0.0079 10 X 0.10 C A B 2.100 0.05 С NOTE 3 0.0827 **BOTTOM VIEW** 0.400 0.0157 **PITCH** 10 X 0.225 0.0089 SCALE 20:1

\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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